

Power Amplifier Support Components

EVALUATION KIT

Fast, easy breadboarding of circuits using the PA75CX are possible with the EK33 PC board. Mounting holes are provided and the provision for standard banana jacks simplifies connection and testing. Components are labeled on both sides of the board for ease in probing. This kit is not suitable for PA75CC or PA75CD. A multitude of circuit configurations are possible, so only several component locations have specific functions and will usually be necessary.

PARTS LIST

Part #	Description	Quantity
Eval33	Evaluation Board	1
Clamp04	Clamp for HS29	2
MS11	Pin Recp., Strip of 30	1
TW14	Thermal Washer TO-220 10/Pack	1
HS29	Heat Sink, 2.7 DEG/W	1

HEATSINKS



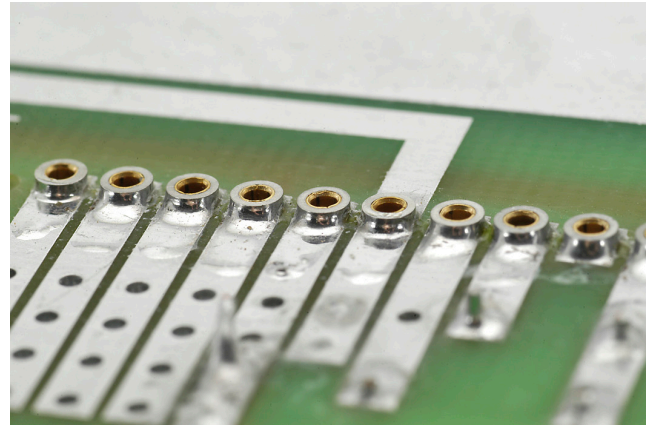
HS29 2.7°C/W

Many heatsinks can be used with this amplifier if a holes is drilled and deburred. Requirements for the potential heatsink or chassis member are flatness of 2 mils per inch in an area large enough to fit the package.

CAGE JACKS

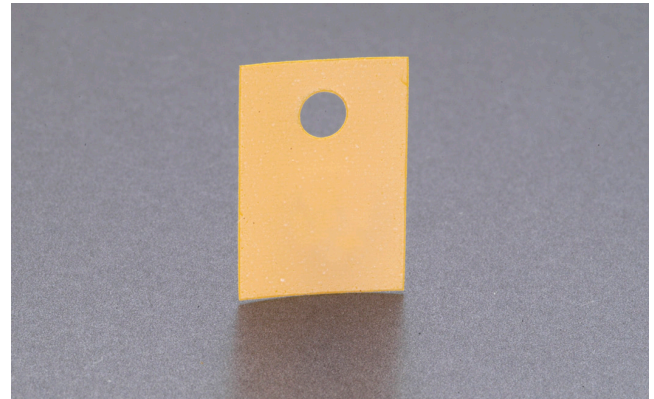


MS11



Part number MS11 consists of a carrier strip of 30 cage jacks. The strip can easily be cut to any desired number of cage jacks. These are mounted directly in a print circuit board. After soldering, the carrier is pulled off the cage jacks. Use a spacer between the PCB and the heatsink to avoid short circuits.

THERMAL WASHER



TW14

NOTES:

1. Base material is aluminum, 0.002" thick. Do not allow the washer to touch pins of the amplifier.
2. For optimum thermal transfer, avoid abrasive handling of washers which can damage their 0.5mil thick layer of thermal compound with which each side is coated.
3. The dry thermal compound will flow filling header to heatsink voids as soon as the material reached 60°C.
4. Do not store unused thermal washers above 40°C.
5. A new washer must be used for each mounting.
6. Part number TW14 consists of a package of 10 washers.
7. Thermal resistance is 0.17°C/W. mal compound with which each side is coated.